

WNM2034

N-Channel, 20V, 3.6A, Power MOSFET

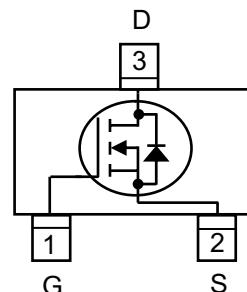
V_{DS} (V)	$R_{DS(on)}$ (Ω)
20	0.037 @ 10V
	0.045 @ 4.5V



SOT-23

Descriptions

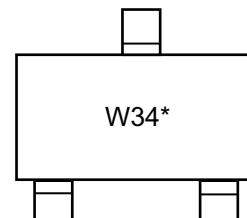
The WNM2034 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. This device is suitable for use in DC-DC conversion and power switch applications. Standard Product WNM2034 is Pb-free.



Configuration (Top View)

Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package SOT-23



W34 = Device Code
* = Month (A~Z)

Marking

Applications

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch

Order Information

Device	Package	Shipping
WNM2034-3/TR	SOT-23	3000/Tape&Reel

WNM2034
ABSOLUTE MAXIMUM RATINGS TA = 25 °C, unless otherwise noted

Parameter	Symbol	10 S	Steady State	Unit
Drain-Source Voltage	V _{DS}	20		V
Gate-Source Voltage	V _{GS}	±12		
Continuous Drain Current (T _J = 150 °C) ^a	T _A =25°C	I _D	3.6	A
	T _A =70°C		2.8	
Maximum Power Dissipation ^a	T _A =25°C	P _D	0.8	W
	T _A =70°C		0.5	
Continuous Drain Current (T _J = 150 °C) ^b	T _A =25°C	I _D	3.2	A
	T _A =70°C		2.6	
Maximum Power Dissipation ^b	T _A =25°C	P _D	0.6	W
	T _A =70°C		0.4	
Pulsed Drain Current ^c	I _{DM}		10	A
Operating Junction and Storage Temperature Range	T _J , T _{stg}		-55 to 150	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	t ≤ 10 s	R _{θJA}	125	150
	Steady State		140	
Junction-to-Ambient Thermal Resistance ^b	t ≤ 10 s	R _{θJA}	150	180
	Steady State		165	
Junction-to-Case Thermal Resistance	R _{θJC}	60	75	

- a Surface mounted on FR4 Board using 1 in sq pad size, 1oz Cu.
- b Surface mounted on FR4 board using the minimum recommended pad size, 1oz Cu.
- c Repetitive rating, pulse width limited by junction temperature, t_p=10µs, Duty Cycle=1%
- d Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.

Electronics Characteristics

(Ta=25°C, unless otherwise noted)

WNM2034

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0 V, I _D = 250uA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 16 V, V _{GS} = 0V			1	uA
Gate-to-source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±12V			±100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250uA	1.0	1.5	2.0	V
Drain-to-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 3.6A		37	47	mΩ
		V _{GS} = 4.5V, I _D = 3.0A		45	56	
Forward Transconductance	g _{FS}	V _{DS} = 5 V, I _D = 3.6A		5.3		S
CHARGES, CAPACITANCES AND GATE RESISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1.0 MHz, V _{DS} = 10 V		505		pF
Output Capacitance	C _{OSS}			60		
Reverse Transfer Capacitance	C _{RSS}			50		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 10 V, I _D = 3.1A		11.4		nC
Threshold Gate Charge	Q _{G(TH)}			0.90		
Gate-to-Source Charge	Q _{GS}			1.18		
Gate-to-Drain Charge	Q _{GD}			2.1		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	td(ON)	V _{GS} = 10 V, V _{DS} = 10 V, R _L =3 Ω, R _G =6 Ω		4.4		ns
Rise Time	tr			3.2		
Turn-Off Delay Time	td(OFF)			24.5		
Fall Time	tf			3.2		
SOURCE-to-DRAIN DIODE CHARACTERISTICS						
Forward Voltage	V _{SD}	V _{GS} = 0 V, I _S = 1.5A	0.80	0.95	1.50	V